

Silicon N Channel MOS FET

REJ03G0917-0200 (Previous: ADE-208-1255) Rev.2.00 Sep 07, 2005

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G

1. Gate

2. Drain
 3. Source
 4. Drain

Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- 4 V gate drive device
 - Can be driven from 5 V source
- Suitable for motor drive, DC-DC converter, power switch and solenoid drive

Outline

RENESAS Package code: PRSS0004ZD-A (Package name: DPAK(L)-(1)) RENESAS Package code: PRSS0004ZD-C (Package name: DPAK(S))



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Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	120	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	3	A
Drain peak current	I _{D(pulse)} *1	12	A
Body to drain diode reverse drain current	I _{DR}	3	A
Channel dissipation	Pch∗ ₂	20	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 µs, duty cycle \leq 1%

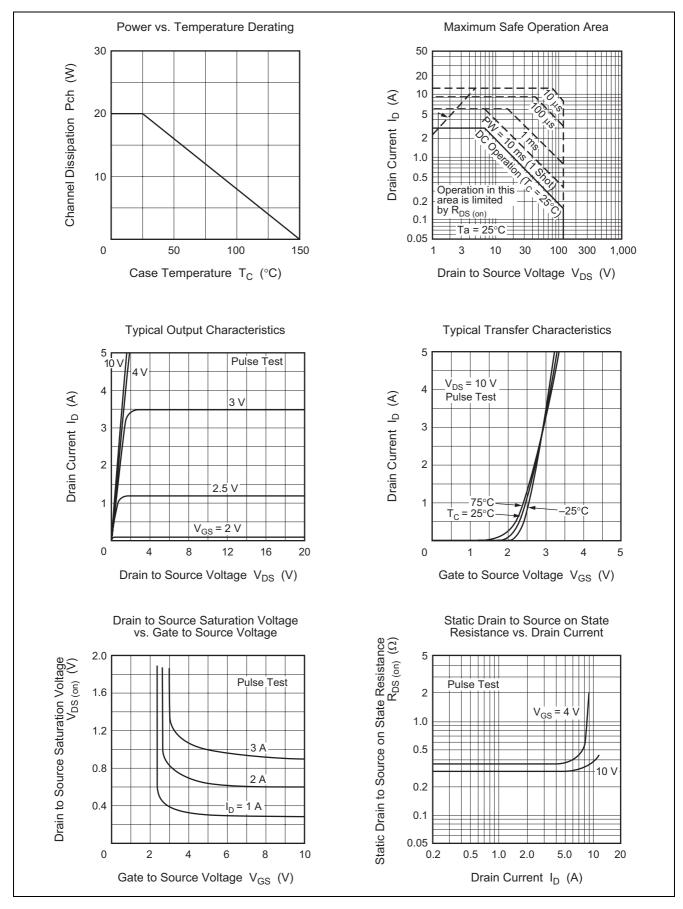
2. Value at $T_C = 25^{\circ}C$

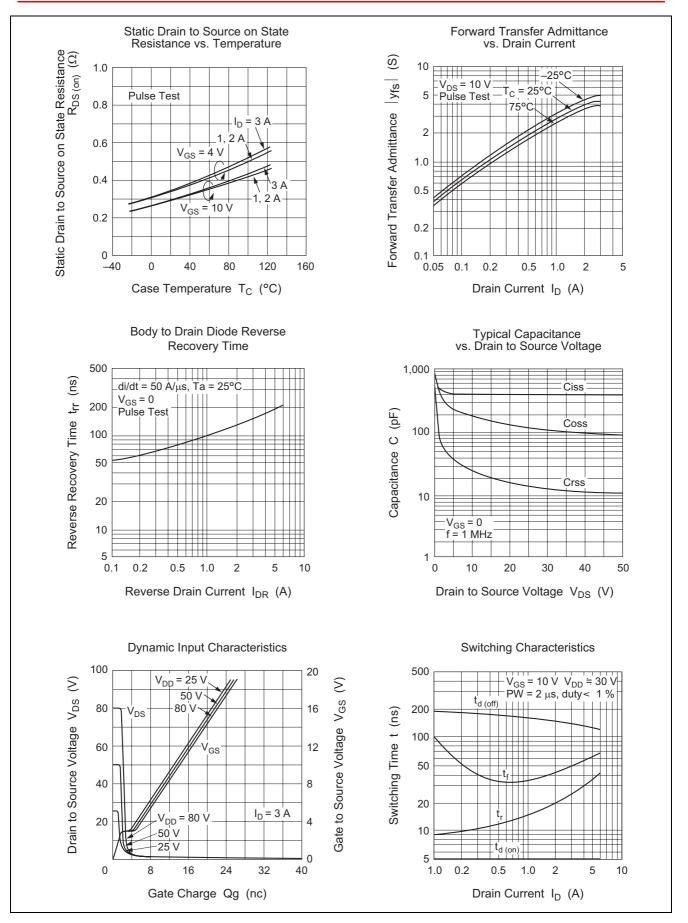
Electrical Characteristics

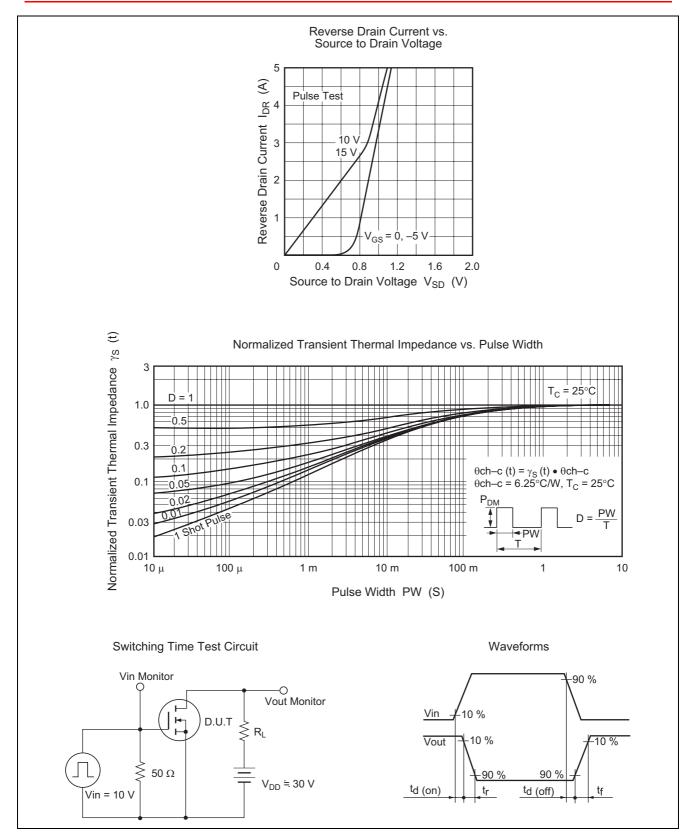
						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	V _{(BR)DSS}	120	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±20	—	_	V	$I_{G} = \pm 100 \ \mu A, V_{DS} = 0$
Gate to source leak current	I _{GSS}	—	—	±10	μA	$V_{GS} = \pm 16 V, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	—	100	μA	$V_{DS} = 100 V, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	1.0	—	2.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state	R _{DS(on)}	_	0.30	0.40	Ω	$I_D = 2 \text{ A}, V_{GS} = 10 \text{ V}^{*3}$
resistance		_	0.35	0.55	Ω	$I_D = 2 A, V_{GS} = 4 V^{*3}$
Forward transfer admittance	y _{fs}	2.4	4.0	_	S	$I_D = 2 \text{ A}, V_{DS} = 10 \text{ V}^{*3}$
Input capacitance	Ciss	_	420	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$ f = 1 MHz
Output capacitance	Coss	_	190	_	pF	
Reverse transfer capacitance	Crss	_	25	_	pF	
Turn-on delay time	t _{d(on)}	_	5	_	ns	$I_D = 2 \text{ A}, V_{GS} = 10 \text{ V},$ $R_L = 15 \Omega$
Rise time	t _r	_	20	_	ns	
Turn-off delay time	t _{d(off)}	_	150	_	ns	
Fall time	t _f	_	45	_	ns	
Body to drain diode forward voltage	V_{DF}		0.95	—	V	$I_F = 3 A, V_{GS} = 0$
Body to drain diode reverse recovery	t _{rr}	_	160	—	ns	$I_F = 3 A, V_{GS} = 0,$
time						di _F /dt = 50 A/µs

Note: 3. Pulse test

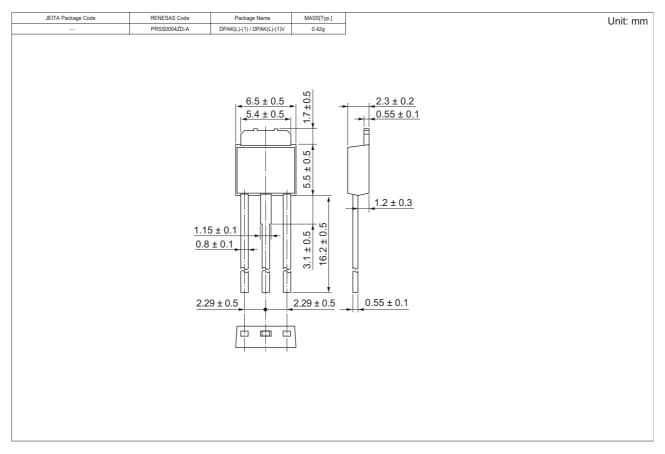
Main Characteristics

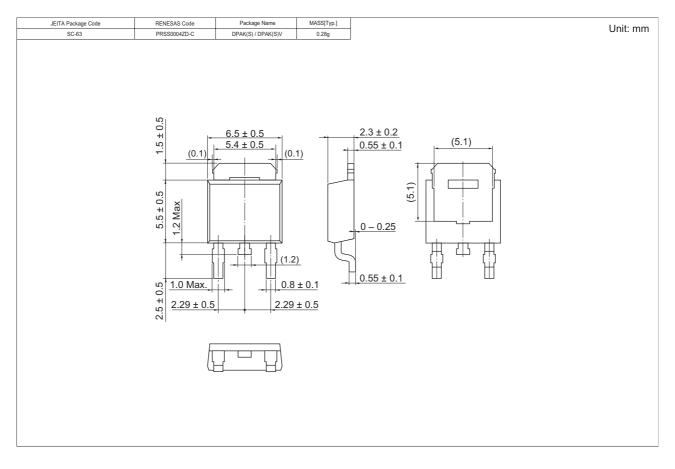






Package Dimensions





Ordering Information

Part Name	Quantity	Shipping Container
2SK1254L-E	3200 pcs	Box (Sack)
2SK1254STL-E	3000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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